Serial No.: 09/692,075

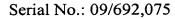
Please replace the first paragraph on page 18 (lines 1-8) with the following amended paragraph:

The final curing process should be performed under a nitrogen atmosphere (oxygen concentration < 100 ppm), with or without a partial vacuum, and should follow the following steps: load the roller 3 with the polyimide coating 4 into oven 7 at < 150°C; increase the temperature to 350°C over a 60 minute period; hold at 350°C for 30 minutes; and, unload the roller 3 with the polyimide coating 4 from oven 7 either immediately or allow it to cool down first. It should be noted that the curing can also be done in an oven without the special atmosphere. The selection of oven atmosphere depends upon a number of factors, such as the size of the area of the polyimide to be cured, the thickness of the final polyimide coating, and other curing factors.

In the Claims:

1. (Amended) A seamless embossing surface configured for transferring data to other surfaces, said embossing surface consisting of a photodefined positive tone polyimide material.





2. (Amended) The embossing surface of claim 1, wherein said polyimide is aqueous developable.

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3. (Amended) The embossing surface of claim 2, wherein said data is transferred to said embossing surface by exposure.

Please delete Claim 7.

- 10. (Amended) A method of embossing data from a seamless embossing surface to other surfaces, said method consisting of the steps of:
- (a) exposing a photo-definable polyimide material to EMF radiation defining said data;

(b) curing said phot-definable material to achieve an embossing surface of a selected hardness; and,

(c) using said embossing surface to emboss said data onto said other surfaces.

15. (Amended) The method of Claim 10, wherein step (b) of curing comprises heating said photo-definable material.

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Serial No.: 09/692,075

28. (Amended) A method of embossing data from a seamless embossing surface to other surfaces, said method comprising the steps of:

- (a) curing a polyimide material to form said embossing surface;
- (b) exposing said embossing surface to EMF radiation defining said data; and,
- (c) applying said embossing surface to transfer data to said other surfaces.

29. (Amended) A method of transferring data from a first seamless surface to other surfaces, said method comprising the steps of:

(a) curing a polyimide material to form said first seamless surface;

external manipulation corresponding to said data; and,

(c) applying said first seamless surface to apply said data to said other surfaces.

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